

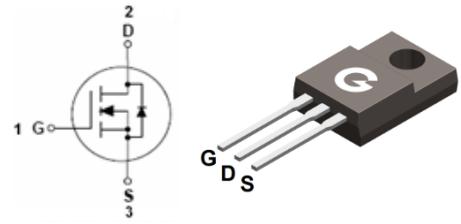
Features

- Fast switching
- Low gate charge
- Low reverse transfer capacitances

HF

Mechanical Data

- Case: ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



ITO-220AB

Ordering Information

| Part Number | Package | Shipping Quantity | Marking Code |
|-------------|-----------|-------------------|--------------|
| BL10N80F | ITO-220AB | 50 pcs / Tube | 10N80F |

Maximum Ratings (@ T_c = 25°C unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|---|------------------|-------|------|
| Drain-to-Source Voltage | V _{DSS} | 800 | V |
| Gate-to-Source Voltage | V _{GSS} | ±30 | V |
| Continuous Drain Current (T _c = 25°C) | I _D | 10 | A |
| Continuous Drain Current (T _c = 100°C) | I _D | 6.5 | A |
| Pulsed Drain Current *1 | I _{DM} | 40 | A |
| Single Pulse Avalanche Energy | E _{AS} | 997 | mJ |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|---|------------------|------------|------|
| Power Dissipation (T _c = 25°C) | P _D | 36 | W |
| Thermal Resistance Junction-to-Air | R _{θJA} | 62.5 | °C/W |
| Thermal Resistance Junction-to-Case | R _{θJC} | 3.47 | °C/W |
| Operating Junction Temperature Range | T _J | -55 ~ +150 | °C |
| Storage Temperature Range | T _{STG} | -55 ~ +150 | °C |

Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Unit |
|---|-----------------------------------|---|------|------|----------|----------|
| Static Characteristics | | | | | | |
| V_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 800 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 800V, V_{GS} = 0V, T_A = 25^\circ\text{C}$ | - | - | 25 | μA |
| | | $V_{DS} = 640V, V_{GS} = 0V, T_A = 125^\circ\text{C}$ | - | - | 250 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ± 10 | μA |
| On Characteristics ^{*2} | | | | | | |
| $R_{DS(ON)}$ | Static Drain-Source On-resistance | $V_{GS} = 10V, I_D = 5A$ | - | - | 0.9 | Ω |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 2 | - | 4 | V |
| gfs | Forward Transconductance | $V_{DS} = 15V, I_D = 10A$ | - | 20 | - | S |
| Dynamic Characteristics | | | | | | |
| C_{ISS} | Input Capacitance | $V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1.0\text{MHz}$ | - | 2900 | - | pF |
| C_{OSS} | Output Capacitance | | - | 200 | - | |
| C_{RSS} | Reverse Transfer Capacitance | | - | 25 | - | |
| Switching Characteristics | | | | | | |
| $t_{d(ON)}$ | Turn-on Delay Time | $V_{DD} = 400V$ $V_{GS} = 10V$ $R_G = 4.7\Omega$ $I_D = 10A$ | - | 19 | - | ns |
| t_r | Turn-on Rise Time | | - | 10 | - | |
| $t_{d(OFF)}$ | Turn-Off Delay Time | | - | 68 | - | |
| t_f | Turn-Off Fall Time | | - | 23 | - | |
| Q_G | Total Gate-Charge | $V_{DD} = 640V$ $V_{GS} = 10V$ $I_D = 10A$ | - | 65 | - | nC |
| Q_{GS} | Gate to Source Charge | | - | 13 | - | |
| Q_{GD} | Gate to Drain (Miller) Charge | | - | 25 | - | |
| Source-Drain Diode Characteristics | | | | | | |
| V_{SD} | Diode Forward Voltage | $I_{SD} = 10A, V_{GS} = 0V$ | - | - | 1.5 | V |
| I_S | Continuous Source Current | | - | - | 10 | A |
| I_{SM} | Pulsed Source Current | | - | - | 40 | A |
| t_{rr} | Reverse Recovery Time | $I_F = 10A, V_{GS} = 0V$ $dI_F/dt = 100A/\mu s$ | - | 200 | - | ns |
| Q_{rr} | Reverse Recovery Charge | | - | 2200 | - | nC |

Notes:

1. Repetitive rating; pulse width limited by maximum junction temperature
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

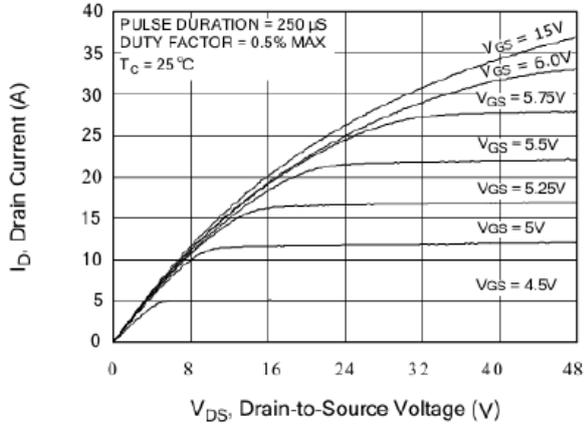


Fig 1 Typical Output Characteristics

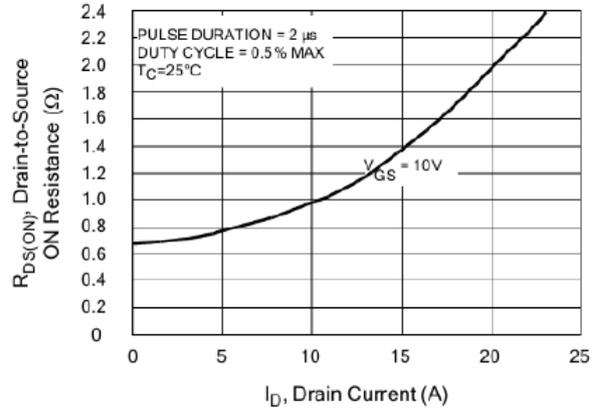


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

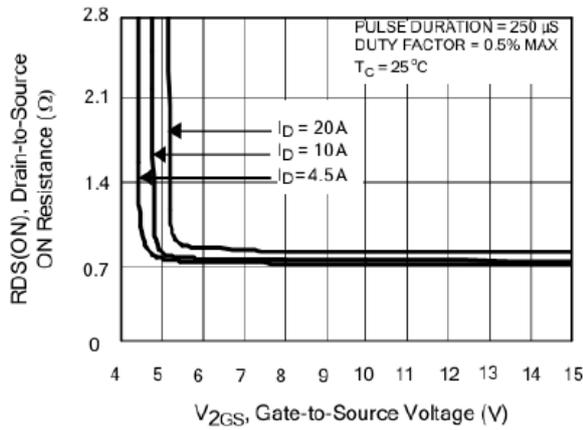


Fig 3 On-Resistance vs. Gate-Source Voltage

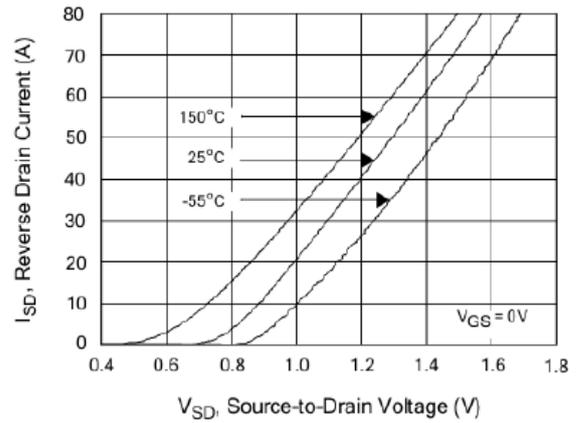


Fig 4 Body-Diode Characteristics

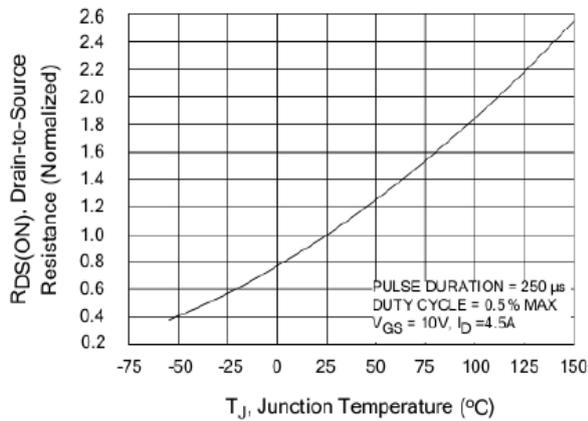


Fig 5 Normalized On-Resistance vs. Junction Temperature

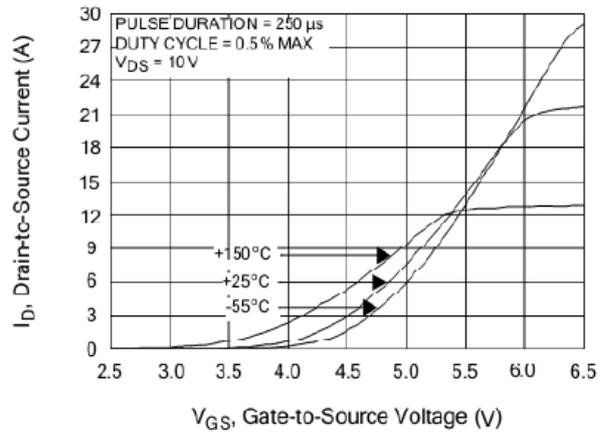


Fig 6 Transfer Characteristics

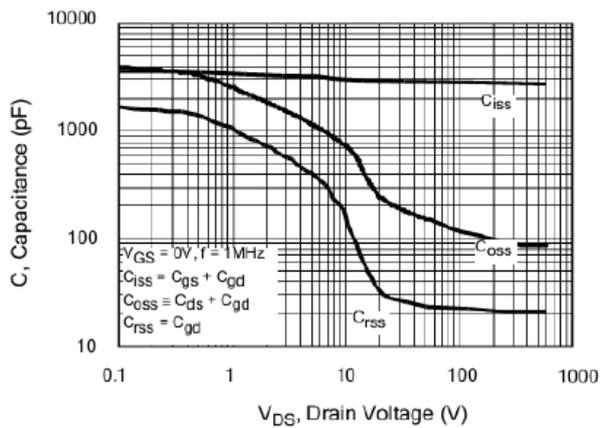


Fig 7 Capacitance Characteristics

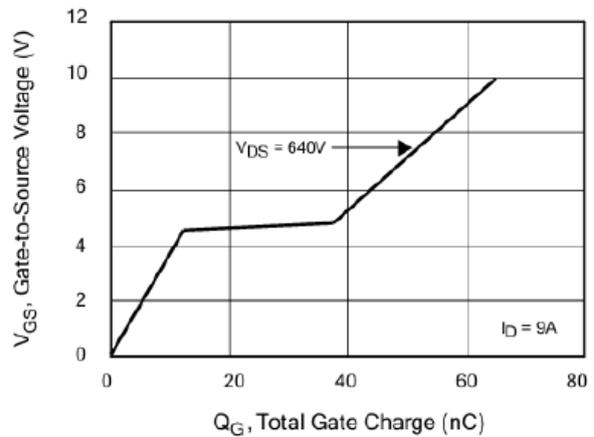


Fig 8 Gate-Charge Characteristics

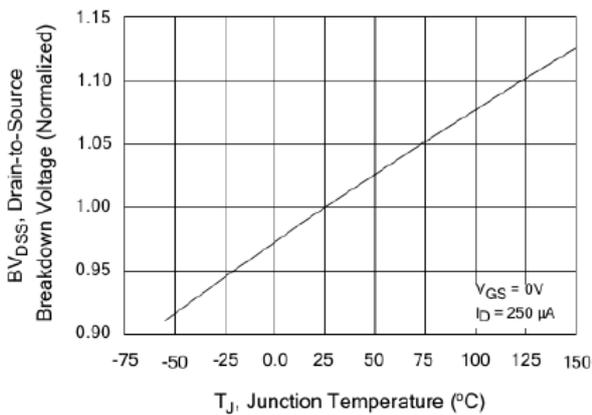


Fig 9 Normalized Breakdown Voltage vs. Junction Temperature

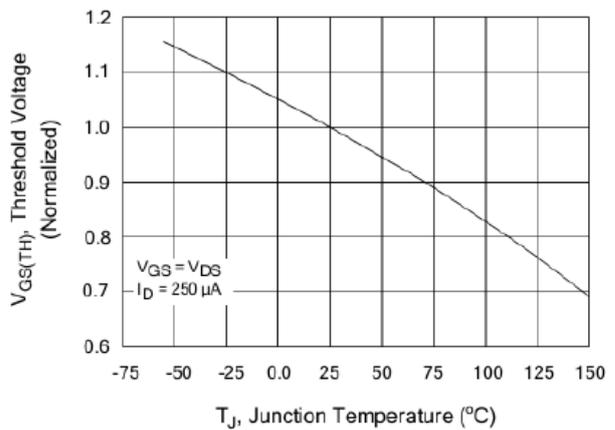


Fig 10 $V_{GS(th)}$ vs. Junction Temperature

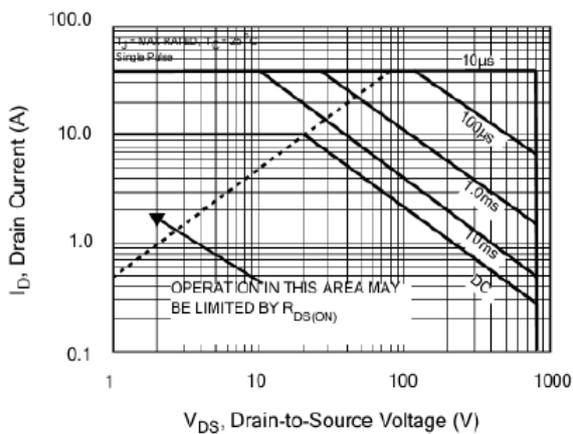


Fig 11 Safe Operation Area

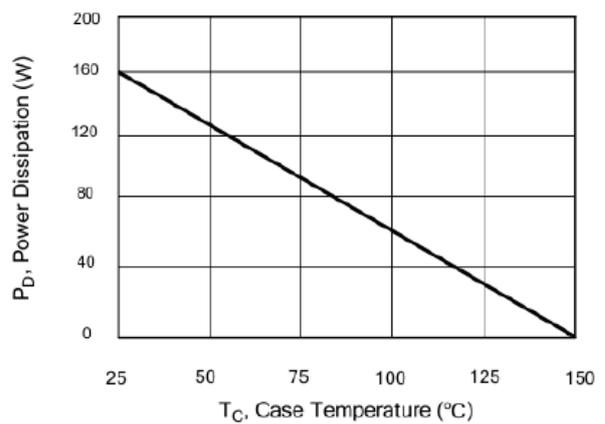


Fig 12 Maximum Power Dissipation vs Case Temperature

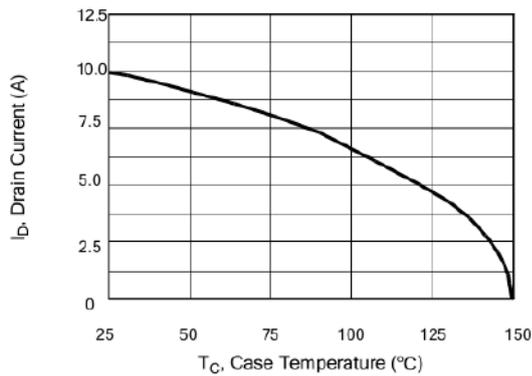


Fig 13 Maximum Continuous Drain Current vs Case Temperature

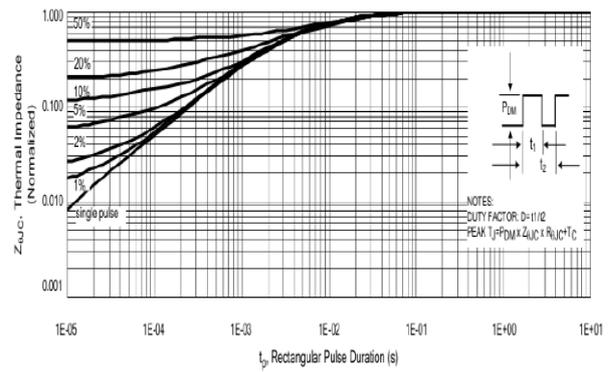
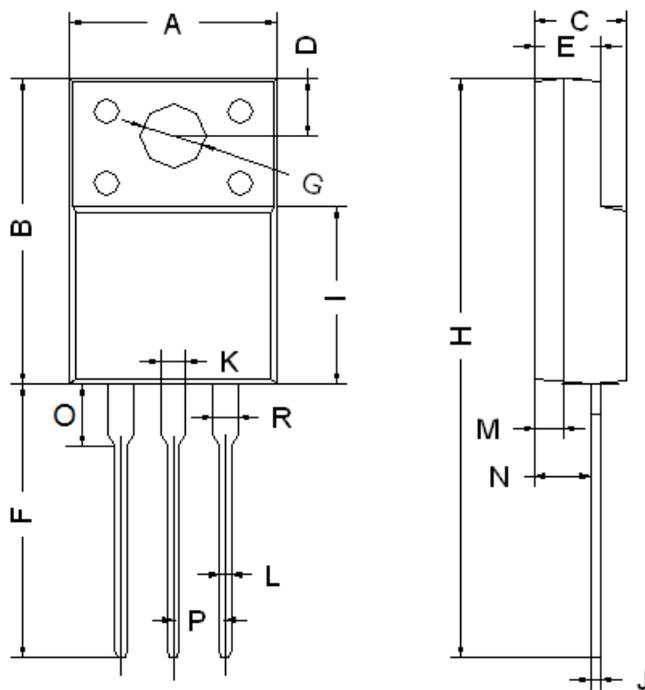


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



| ITO-220AB | | |
|-----------|-------|-------|
| Dimension | Min. | Max. |
| A | 9.90 | 10.30 |
| B | 14.80 | 15.20 |
| C | 4.30 | 4.70 |
| D | 2.50 | 2.90 |
| E | 2.80 | 3.30 |
| F | 13.00 | 13.60 |
| G | 3.10 | 3.30 |
| H | 28.00 | 28.60 |
| I | 7.90 | 8.90 |
| J | 0.40 | 0.60 |
| L | 0.70 | 0.90 |
| M | 1.30 | 1.50 |
| N | 2.60 | 2.80 |
| O | 2.60 | 3.10 |
| P | 2.45 | 2.65 |
| K/R | 1.10 | 1.30 |

Important Notice

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.